

Fig. 1

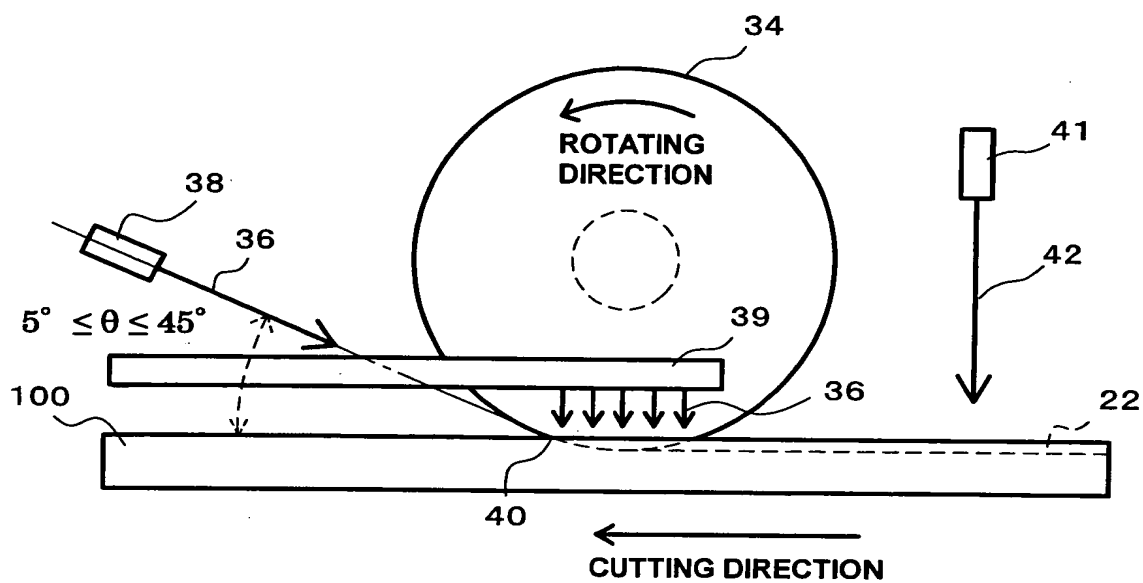


Fig. 2A

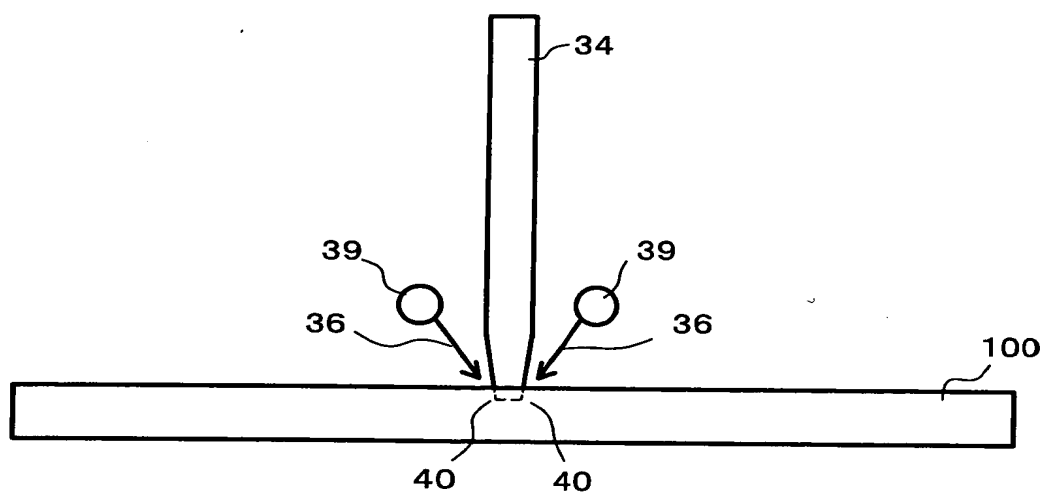


Fig. 2B

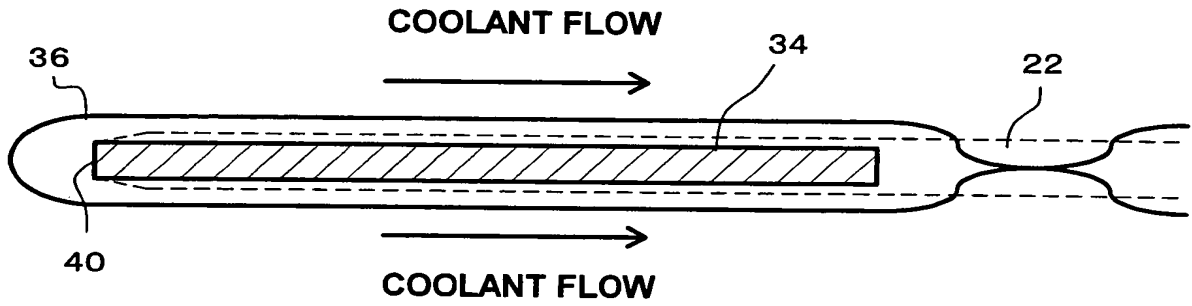


Fig. 3A

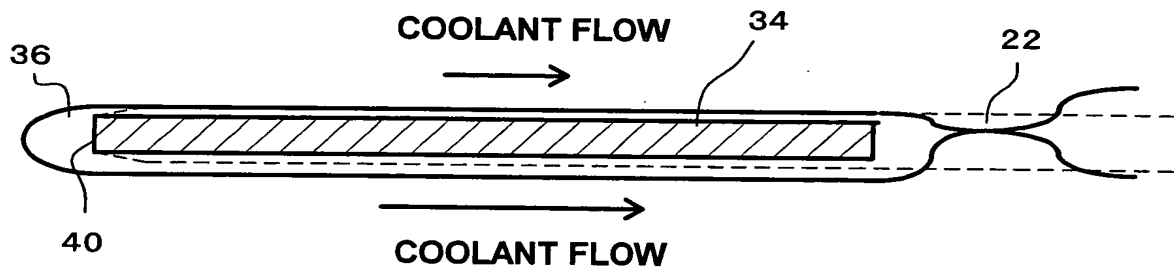


Fig. 3B

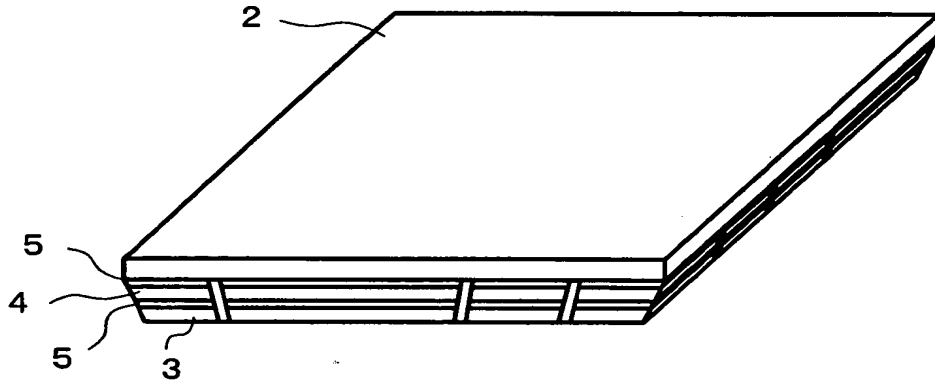


Fig. 4A

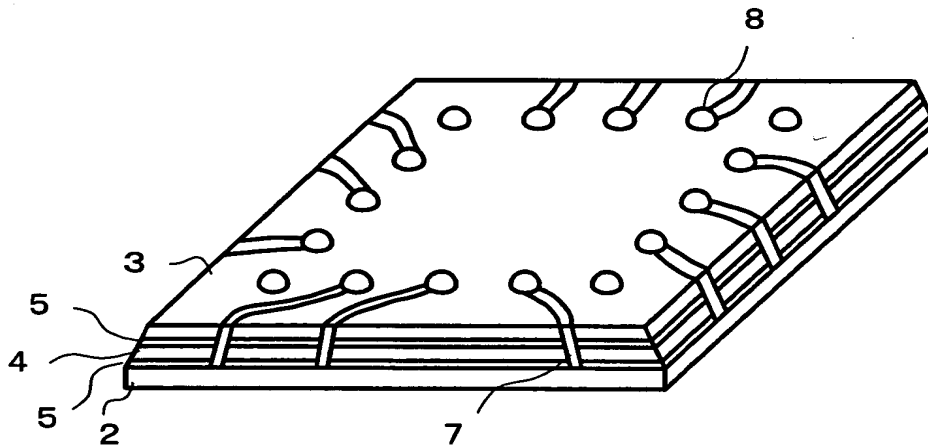


Fig. 4B

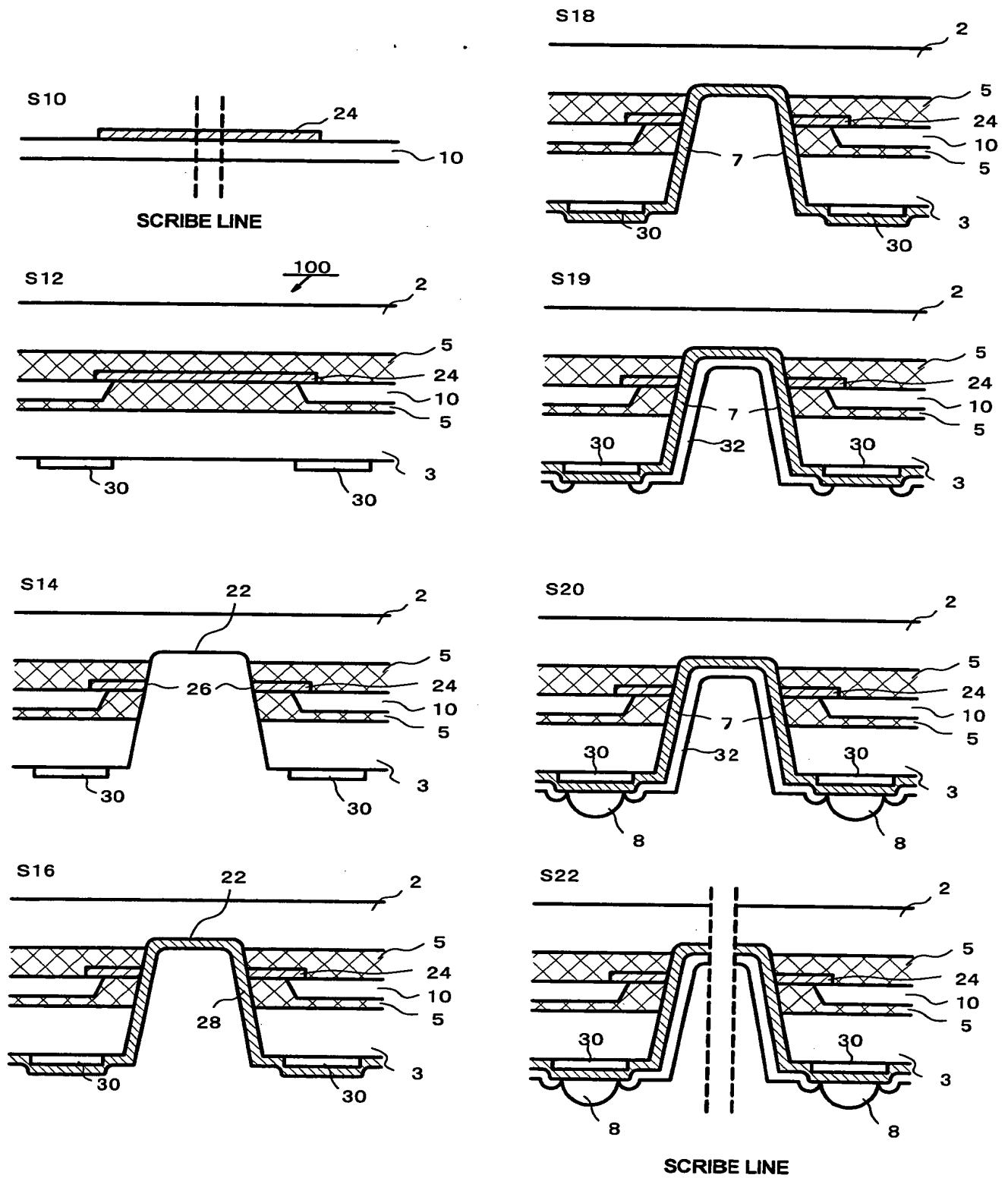


Fig. 5

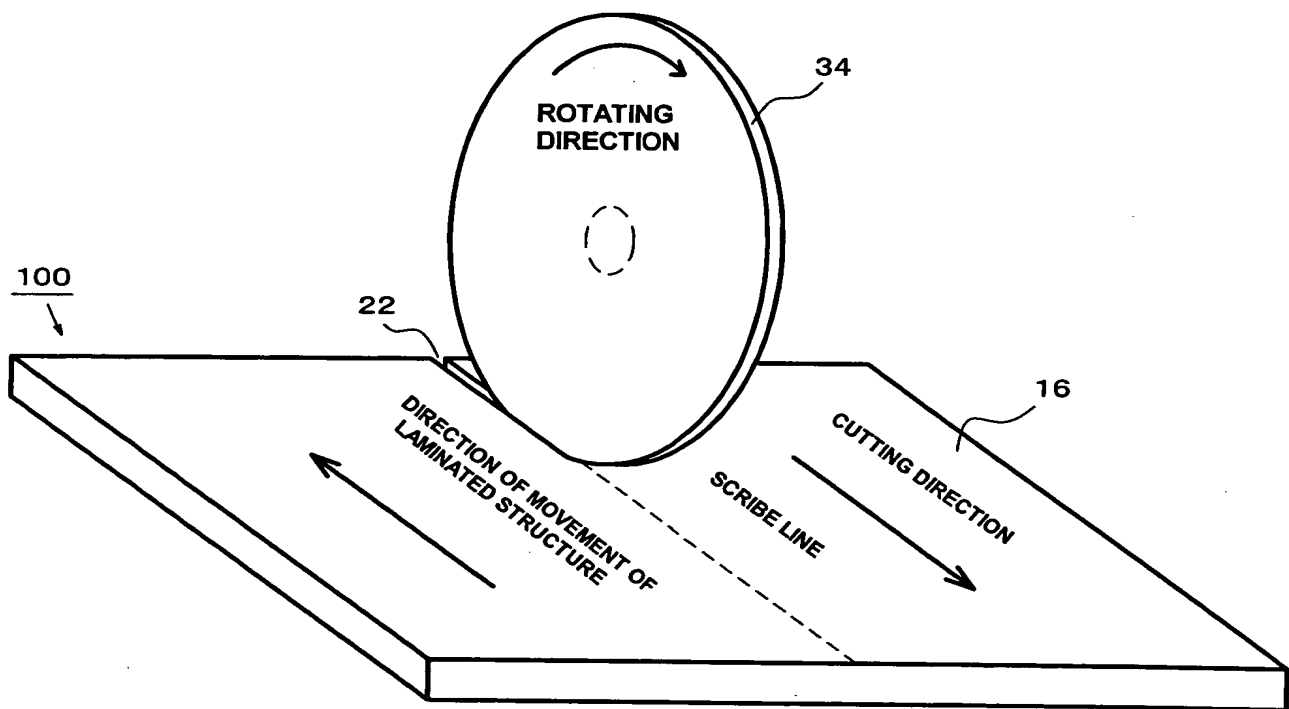


Fig. 6



ABOUT US PRODUCTS PACKAGING SERVICES LICENSING NEWS ROOM CAREERS CONTACT



- ShellOP
- ShellBGA

Overview | Process

On this page you can view the process flow of Shellcase's ShellOP product.

To download the entire presentation in PDF format, click here.

Download PDF

PRODUCTS

Index

[Step A: Passivation and Pad Extension Layers](#)

[Step B: Glass 1 Attachment](#)

[Step C: Backside Silicon Grinding & Scribe Line Etch](#)

[Step D: Glass 2 Attachment](#)

[Step E: Compliant Layer Formation](#)

[Step F: Notch](#)

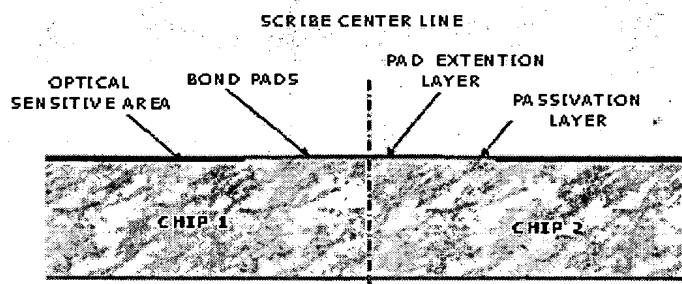
[Step G: External Lead Formation](#)

[Step H: External Passivation](#)

[Step I: BGA Formation](#)

[Step J: Dicing](#)

Step A: Passivation and Pad Extension Layers

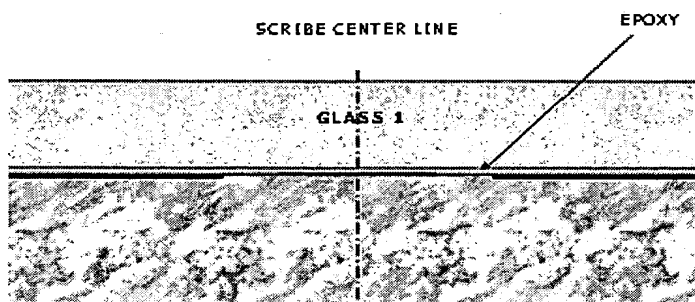


A B C D E F G H I J

Back to Top ▲

Back ◀ Next ▶

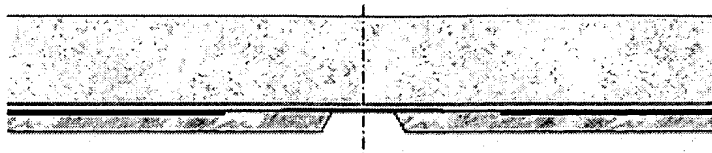
Step B: Glass 1 Attachment



A B C D E F G H I J

[Back to Top](#)[Back](#) [Next](#)**Step C: Backside Silicon Grinding & Scribe Line Etch**

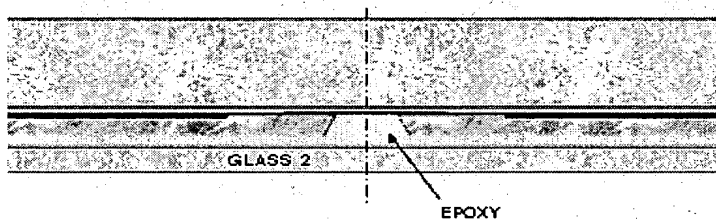
SCRIBE CENTER LINE



A B C D E F G H I J

[Back to Top](#)[Back](#) [Next](#)**Step D: Glass 2 Attachment**

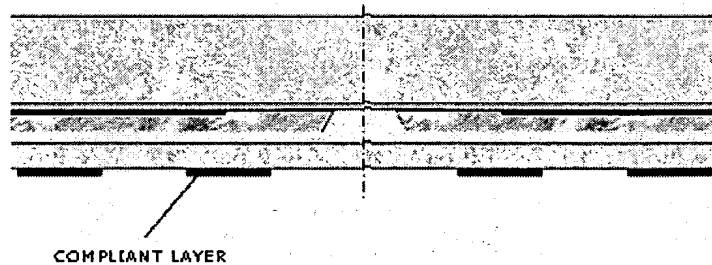
SCRIBE CENTER LINE



A B C D E F G H I J

[Back to Top](#)[Back](#) [Next](#)**Step E: Compliant Layer Formation**

SCRIBE CENTER LINE

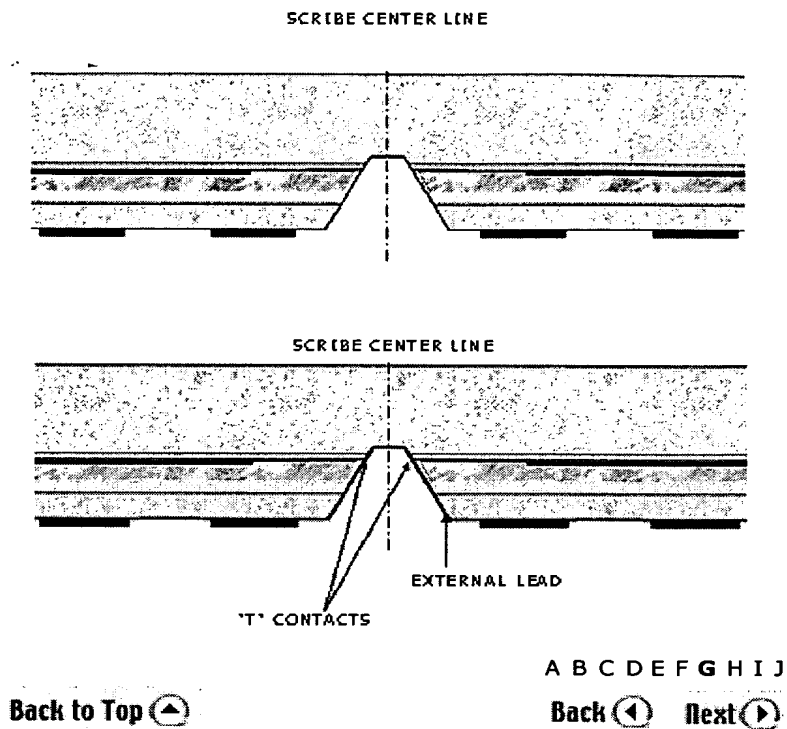


A B C D E F G H I J

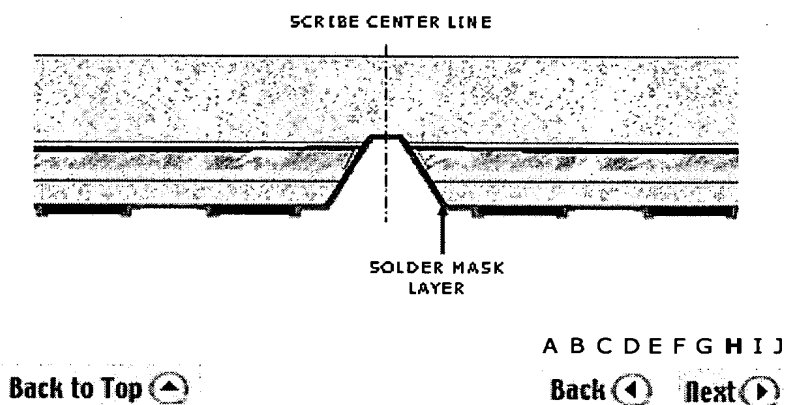
[Back to Top](#)[Back](#) [Next](#)**Step F: Notch**

A B C D E F G H I J

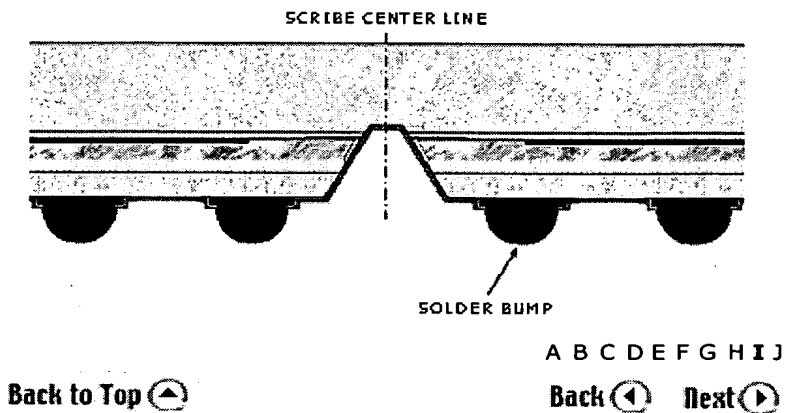
[Back to Top](#)[Back](#) [Next](#)**Step G: External Lead Formation**



Step H: External Passivation

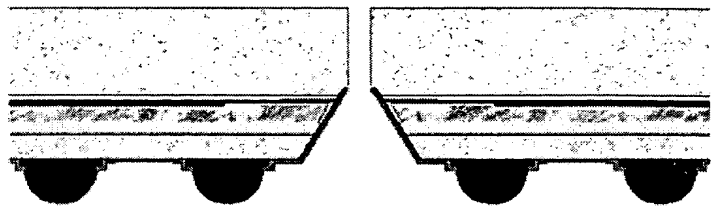


Step I: BGA Formation



Step J: Dicing

SCRIBE CENTER LINE



A B C D E F G H I J

Back to Top 

Back  Next 